

Clock Generator for Intel Eaglelake Chipset

Features

- **Compliant to Intel® CK505**
- **Low power push-pull type differential output buffers**
- **Integrated voltage regulator**
- **Integrated resistors on differential clocks**
- **Scalable low voltage VDD_IO (3.3V to 1.05V)**
- **Differential CPU clocks with selectable frequency**
- **100 MHz Differential SRC clocks**
- **96 MHz Differential DOT clock**
- **48 MHz USB clocks**
- **33 MHz PCI clock**
- **25MHz Free run for WOL**
- **Selectable 25MHz/24.576MHz**
- **Buffered Reference Clock 14.318 MHz**
- **Low-voltage frequency select input**
- **I2C support with readback capabilities**
- **Triangular Spread Spectrum profile for maximum electromagnetic interference (EMI) reduction**
- **3.3V Power supply**
- **64-pin TSSOP packages**

Frequency Select Pin (FSA, FSB and FSC)

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Apply the appropriate logic levels to FSA, FSB, and FSC inputs before CK-PWRGD assertion to achieve host clock frequency selection. When the clock chip sampled HIGH on CK-PWRGD and indicates that VTT voltage is stable then FSA, FSB, and FSC input values are sampled. This process employs a one-shot functionality and once the CK-PWRGD sampled a valid HIGH, all other FSA, FSB, FSC, and CK-PWRGD transitions are ignored except in test mode

Serial Data Interface

To enhance the flexibility and function of the clock synthesizer, a two-signal serial interface is provided. Through the Serial Data Interface, various device functions, such as individual clock output buffers are individually enabled or disabled. The registers associated with the Serial Data Interface initialize to their default setting at power-up. The use of this interface is

optional. Clock device register changes are normally made at system initialization, if any are required. The interface cannot be used during system operation for power management functions.

Data Protocol

The clock driver serial protocol accepts byte write, byte read, block write, and block read operations from the controller. For block write/read operation, Access the bytes in sequential order from lowest to highest (most significant bit first) with the ability to stop after any complete byte is transferred. For byte write and byte read operations, the system controller can access individually indexed bytes. The offset of the indexed byte is encoded in the command code described in *[Table 1](#page-5-0)*.

The block write and block read protocol is outlined in *[Table 2](#page-5-1)* while *[Table 3](#page-6-0)* outlines byte write and byte read protocol. The slave receiver address is 11010010 (D2h)

Table 1. Command Code Definition

Table 2. Block Read and Block Write Protocol

Table 2. Block Read and Block Write Protocol (continued)

Table 3. Byte Read and Byte Write Protocol

Control Registers

Byte 0: Control Register 0

Byte 1: Control Register 1

Byte 2: Control Register 2

Byte 3: Control Register 3

Byte 4: Control Register 4

Byte 5: Control Register 5

Byte 5: Control Register 5 (continued)

Byte 6: Control Register 6

Byte 7: Vendor ID

Byte 8: Control Register 8

Byte 8: Control Register 8 (continued)

Byte 9: Control Register 9

Byte 10: Control Register 10

Byte 11: Control Register 11

Byte 11: Control Register 11 (continued)

Byte 12: Byte Count

Byte 13: Control Register 13

Byte 14: Control Register 14

Byte 15: Control Register 15

Byte 16: Control Register 16

Byte 17: Control Register 17

Byte 18: Control Register 18

Table 4. Crystal Recommendations

The SL28504 requires a Parallel Resonance Crystal. Substituting a series resonance crystal causes the SL28504 to operate at the wrong frequency and violates the ppm specification. For most applications there is a 300-ppm frequency shift between series and parallel crystals due to incorrect loading

Crystal Loading

Crystal loading plays a critical role in achieving low ppm performance. To realize low ppm performance, use the total capacitance the crystal sees to calculate the appropriate capacitive loading (CL).

[Figure 1](#page-13-0) shows a typical crystal configuration using the two trim capacitors. It is important that the trim capacitors are in series with the crystal. It is not true that load capacitors are in parallel with the crystal and are approximately equal to the load capacitance of the crystal.

Figure 1. Crystal Capacitive Clarification

Calculating Load Capacitors

In addition to the standard external trim capacitors, consider the trace capacitance and pin capacitance to calculate the

crystal loading correctly. Again, the capacitance on each side is in series with the crystal. The total capacitance on both side is twice the specified crystal load capacitance (CL). Trim capacitors are calculated to provide equal capacitive loading on both sides.

Figure 2. Crystal Loading Example

Use the following formulas to calculate the trim capacitor values for Ce1 and Ce2.

Load Capacitance (each side)

$$
Ce = 2 \cdot CL - (Cs + Ci)
$$

Total Capacitance (as seen by the crystal)

$$
CLe = \frac{1}{\left(\frac{1}{Ce1 + Cs1 + Ci1} + \frac{1}{Ce2 + Cs2 + Ci2}\right)}
$$

Dial-A-Frequency® (CPU and PCIEX)

This feature allows the user to over-clock their system by slowly stepping up the CPU or SRC frequency. When the programmable output frequency feature is enabled, the CPU and SRC frequencies are determined by the following equation:

Fcpu = $G * N/M$ or Fcpu=G2 $* N$, where G2 = G / M.

- "N" and "M" are the values programmed in Programmable Frequency Select N-Value Register and M-Value Register, respectively.
- "G" stands for the PLL Gear Constant, which is determined by the programmed value of FS[E:A]. See *[Table](#page-5-2)* , *Frequency Select Table* for the Gear Constant for each Frequency selection. The PCI Express only allows user control of the N register, the M value is fixed and documented in *[Table](#page-5-2)* , *Frequency Select Table*.

In this mode, the user writes the desired N and M values into the DAF I2C registers. The user cannot change only the M value and must change both the M and the N values at the same time, if they require a change to the M value. The user may change only the N value.

Associated Register Bits

- *CPU_DAF Enable* This bit enables CPU DAF mode. By default, it is not set. When set, the operating frequency is determined by the values entered into the CPU_DAF_N_ register. Note that the CPU_DAF_N and M register must contain valid values before CPU_DAF is set. Default = 0, (No DAF).
- *CPU_DAF_N* There are nine bits (for 512 values) to linearly change the CPU frequency (limited by VCO range). Default = 0 , (0000). The allowable values for N are detailed in *[Table](#page-5-2)* , *Frequency Select Table*.
- *CPU DAF M* There are 7 bits (for 128 values) to linearly change the CPU frequency (limited by VCO range). Default = 0, the allowable values for M are detailed in *[Table](#page-5-2)* , *Frequency Select Table*
- *SRC_DAF Enable* This bit enables SRC DAF mode. By default, it is not set. When set, the operating frequency is determined by the values entered into the SRC_DAF_N register. Note that the SRC_DAF_N register must contain valid values before SRC DAF is set. Default = 0, (No DAF).
- *SRC_DAF_N* There are nine bits (for 512 values) to linearly change the CPU frequency (limited by VCO range). Default = 0 , (0000). The allowable values for N are detailed in *[Table](#page-5-2)* , *Frequency Select Table*.

Smooth Switching

The device contains one smooth switch circuit that is shared by the CPU PLL and SRC PLL. The smooth switch circuit ensures that when the output frequency changes by overclocking, the transition from the old frequency to the new frequency is a slow, smooth transition containing no glitches. The rate of change of output frequency when using the smooth switch circuit is less than 1 MHz/0.667 μ s. The frequency overshoot and undershoot is less than 2%.

The Smooth Switch circuit assigns auto or manual. In Auto mode, clock generator assigns smooth switch automatically when the PLL does overclocking. For manual mode, assign the smooth switch circuit to PLL via Smbus. By default the smooth switch circuit is set to auto mode. PLL can be over-clocked when it does not have control of the smooth switch circuit but it is not guaranteed to transition to the new frequency without large frequency glitches.

Do not enable over-clocking and change the N values of both PLLs in the same SMBUS block write and use smooth switch mechanism on spread spectrum on/off.

PD_RESTORE

If a '0' is set for Byte 0 bit 0 then, upon assertion of PWRDWN# LOW, the SL28504 initiates a full reset. The result of this is that the clock chip emulates a cold power on start and goes to the "Latches Open" state. If the PD_RESTORE bit is set to a '1' then the configuration is stored upon PWRDWN# asserted LOW. Note that if the iAMT bit, Byte 0 bit 3, is set to a '1' then the PD_RESTORE bit must be ignored. In other words, in Intel iAMT mode, PWRDWN# reset is not allowed.

PWRDWN# (Power down) Clarification

The CKPWRGD/PWRDWN# pin is a dual-function pin. During initial power up, the pin functions as CKPWRGD. Once CKPWRGD has been sampled HIGH by the clock chip, the pin assumes PD# functionality. The PD# pin is an asynchronous active LOW input used to shut off all clocks cleanly before shutting off power to the device. This signal is synchronized internally to the device before powering down the clock synthesizer. PD# is also an asynchronous input for powering up the system. When PD# is asserted LOW, clocks are driven to a LOW value and held before turning off the VCOs and the crystal oscillator.

PWRDWN# (Power down) Assertion

When PD is sampled HIGH by two consecutive rising edges of CPUC, all single-ended outputs will be held LOW on their next HIGH-to-LOW transition and differential clocks must held LOW. When PD mode is desired as the initial power on state, PD must be asserted HIGH in less than 10 μ s after asserting CKPWRGD.

PWRDWN# Deassertion

The power up latency is less than 1.8 ms. This is the time from the deassertion of the PD# pin or the ramping of the power supply until the time that stable clocks are generated from the clock chip. All differential outputs stopped in a three-state condition, resulting from power down are driven high in less than 300 μ s of PD# deassertion to a voltage greater than 200 mV. After the clock chip's internal PLL is powered up and locked, all outputs are enabled within a few clock cycles of

each clock. *[Figure 4](#page-15-0)* is an example showing the relationship of clocks coming up.

Figure 4. Power down Deassertion Timing Waveform

Figure 5. CK_PWRGD Timing Diagram

CPU_STP# Assertion

The CPU_STP# signal is an active LOW input used for synchronous stopping and starting the CPU output clocks while the rest of the clock generator continues to function. When the CPU_STP# pin is asserted, all CPU outputs that are set with the SMBus configuration to be stoppable are stopped within two to six CPU clock periods after sampled by two rising edges of the internal CPUC clock. The final states of the stopped CPU signals are CPUT = HIGH and CPUC = LOW.

CPU_STP# Deassertion

The deassertion of the CPU_STP# signal causes all stopped CPU outputs to resume normal operation in a synchronous manner. No short or stretched clock pulses are produced when the clock resumes. The maximum latency from the deassertion to active outputs is no more than two CPU clock cycles.

Figure 7. CPU_STP# Deassertion Waveform

Figure 8. CPU_STP# = Driven, CPU_PD = Driven, DOT_PD = Driven

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PCI_STP# Assertion

The PCI_STP# signal is an active LOW input used for synchronously stopping and starting the PCI outputs while the rest of the clock generator continues to function. The set-up time for capturing PCI_STP# going LOW is 10 ns (t_{S1}) . (See *[Figure 10](#page-18-0)*.) The PCIF clocks are affected by this pin if their corresponding control bit in the SMBus register is set to allow them to be free running.

Figure 10. PCI_STP# Assertion Waveform

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PCI_STP# Deassertion

The deassertion of the PCI_STP# signal causes all PCI and stoppable PCIF clocks to resume running in a synchronous manner within two PCI clock periods, after PCI STP# transitions to a HIGH level.

. **Table 5. Output Driver Status during PCI-STOP# and CPU-STOP#**

Table 6. Output Driver Status

Figure 12. Clock Generator Power up/Run State Diagram

SL28504

Figure 13. BSEL Serial Latching

Absolute Maximum Conditions

Multiple Supplies: The Voltage on any input or I/O pin cannot exceed the power pin during power-up. Power supply sequencing is NOT required.

DC Electrical Specifications

DC Electrical Specifications

AC Electrical Specifications

AC Electrical Specifications (continued)

AC Electrical Specifications (continued)

AC Electrical Specifications (continued)

Test and Measurement Set-up

For PCI Single-ended Signals and Reference

The following diagram shows the test load configurations for the single-ended PCI, USB, and REF output signals.

Figure 14. Single-ended PCI and USB Double Load Configuration

Figure 15. Single-ended REF Triple Load Configuration

Figure 16. Single-ended Output Signals (for AC Parameters Measurement)

For CPU, SRC, and DOT96 Signals and Reference

This diagram shows the test load configuration for the differential CPU and SRC outputs

Figure 17. 0.7V Differential Load Configuration

Figure 18. Differential Measurement for Differential Output Signals (for AC Parameters Measurement)

Ordering Information

64-Lead Thin Shrunk Small Outline Package (6 mm x 17 mm) Z64

Document History Page

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